

**A PROCESS OF FORMING METAL SURFACES COMPATIBLE WITH A  
WIRE BONDING AND SEMICONDUCTOR INTEGRATED CIRCUITS  
MANUFACTURED BY THE PROCESS**

Abstract of the Disclosure

5           The present invention relates to the structure and process of forming metal  
surfaces on the bare metal interconnect of a semiconductor chip. The metal chip  
comprises metal interconnect formed on a semiconductor substrate and at least a portion  
of the metal interconnect is exposed to the environment. In one aspect of the invention,  
the process comprises applying a noble metal on the exposed portion of the metal  
10 interconnect and performing a chemical process that causes a layer of the noble metal to  
convert into a bondable layer compatible with a conventional wire bonding. The process  
also comprises bonding a metal wire to the bondable layer.

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